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(54) **METHOD OF BONDING PERMEABLE SUBSTRATES WITH HOT MELT MOISTURE CURE ADHESIVE HAVING LOW VISCOSITY AND HIGH GREEN STRENGTH**

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(57) **ABSTRACT**

The present invention relates to a hot melt moisture cure adhesive composition well suited for bonding porous substrates such as fabric, methods of adhesively bonding substrates and corresponding articles. The adhesive composition exhibits a combination of flexibility, high green strength, low molten viscosity and high heat resistance. In view of these properties, the adhesive is particularly amendable to hot melt adhesive application techniques wherein small individual discrete deposits of adhesive are applied to a substrate. The adhesive composition prepolymer is preferably the reaction product of at least one polyol, at least one polyisocyanate and at least one high molecular weight thermoplastic polyurethane lacking hard segments.

28 Claims, No Drawings